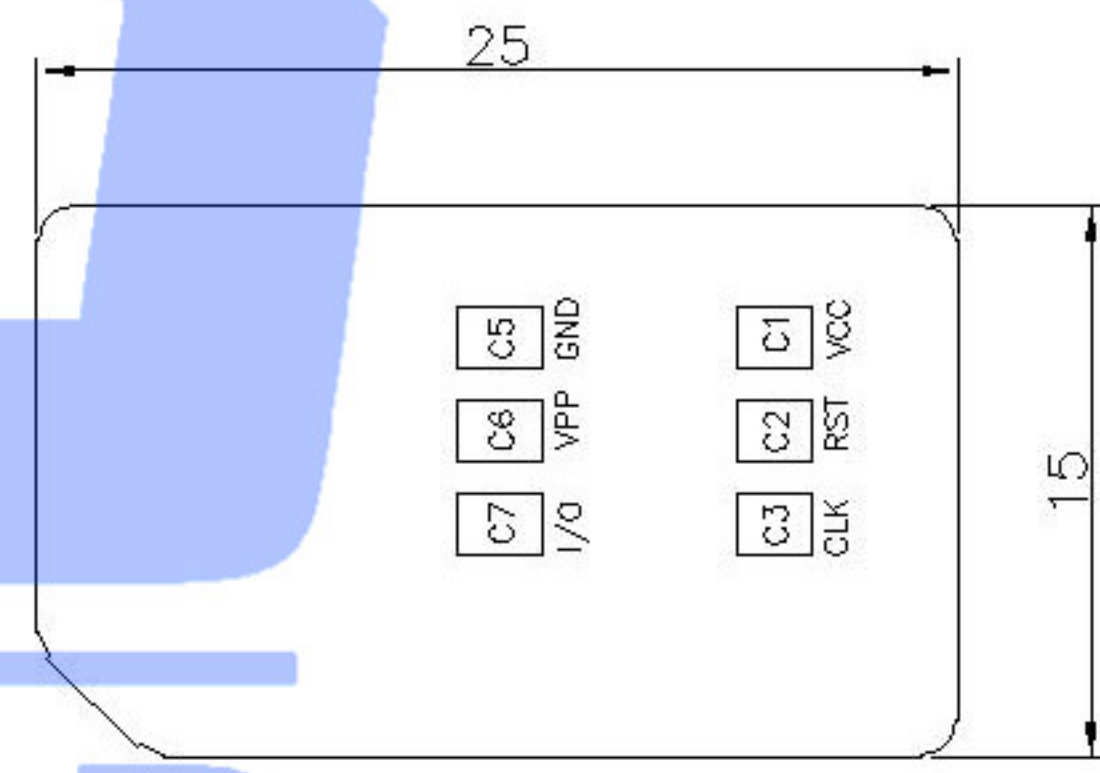
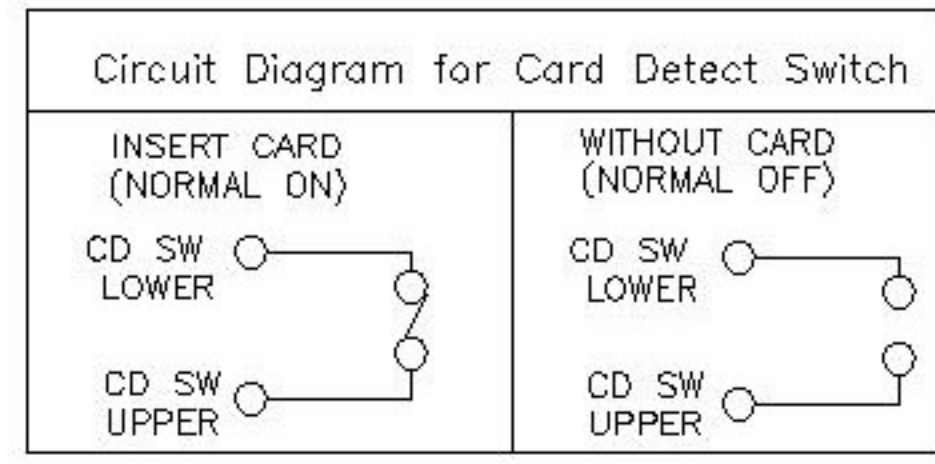
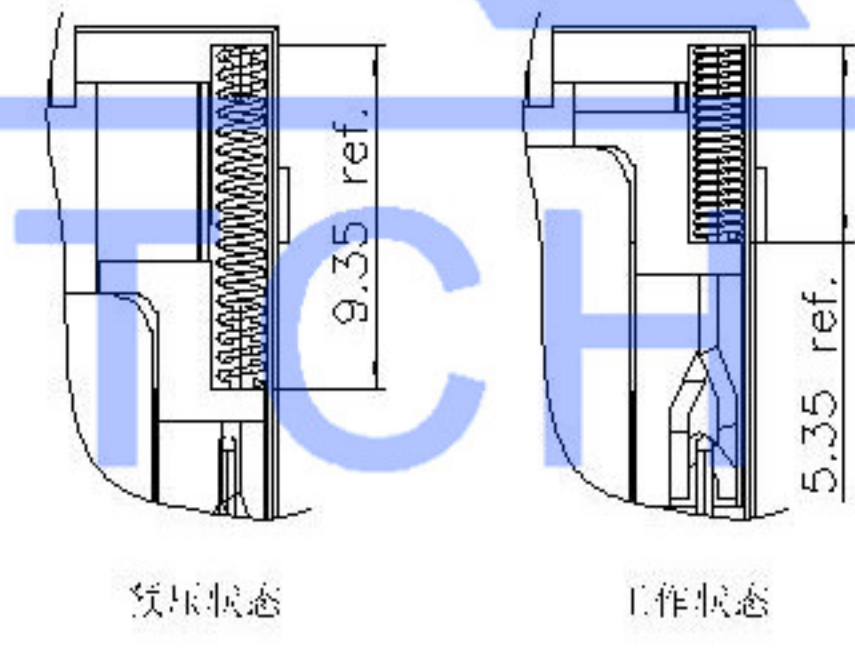


NOTES:
 1) MATERIAL:
 HOUSING: LCP UL 94V-0
 TERMINAL: COPPER ALLOY ,T=0.15
 SHELL: SUS,T=0.15
 MYLAR: POLYESTER
 2) FINISH :
 TERMINAL: GOLD FLASH PLATED ON CONTACT AREA;
 GOLD FLASH PLATING ON SOLDER TAILS, WITH
 ENTIRE CONTACT UNDERPLATED
 50u"Min, NICKEL
 SHELL: 50u"Min. NICKEL UNDERPLATED OVERALL ,
 GOLD FLASH PLATED ON SOLDER TAILS
 3) INFRARED REFLOW SOLDERING: 10sec. Min. at 260±10



PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL
P8#	DET

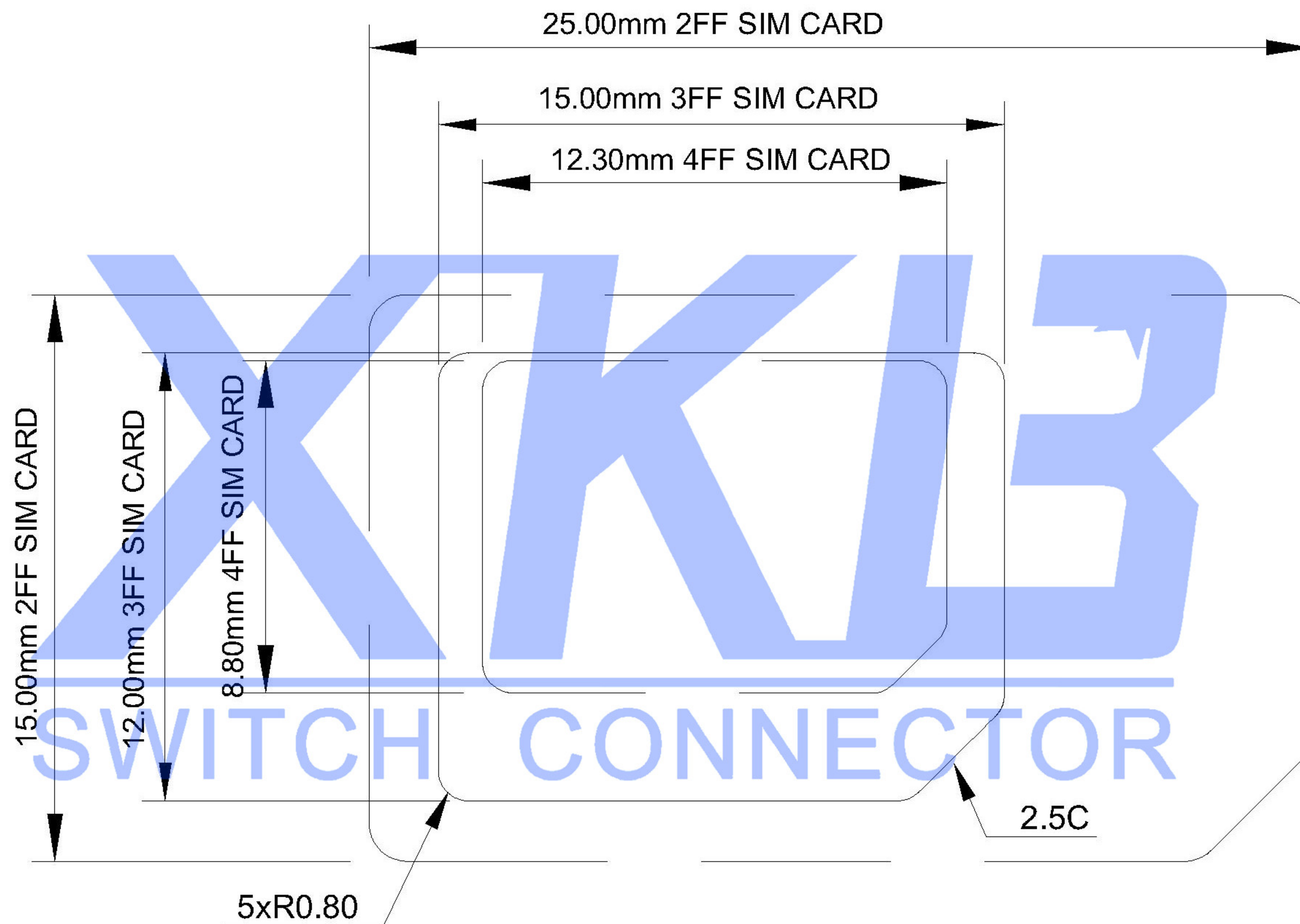


ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING
③	Shell	1	SUS	
②	Terminal	8	COPPER ALLOY	
①	Housing	1	LCP UL 94V-0	BLACK

MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES	DSND	DATE	SCALE: N/A	MODEL TYPE: SIM CARD CONN
△X					ANGLAR ±5°	DWN	DATE	VIEW:	PART NO.:
△X					L ≤ 4 ±0.2	CHKD	DATE	UNIT: mm	DWG NO.:
△X					4 < L ≤ 16 ±0.3	APPD	DATE	SIZE: A4	XKSIM-115
					16 < L ≤ 63 ±0.4				WEIGHT 1.0g
					L > 63 ±0.5				SHEET 1/1
									REVISION A0

REVISIONS
 www.xk-dg.cn www.helloxkb.com www.helloxkb.cn

XKB INDUSTRIAL PRECISION CO., LIMITED



					ANGLAR	±5°	DSND		DATE		SCALE: N/A	MODEL TYPE: SIM CARD CONN	
△X					L ≤ 4	±0.2	DWN		DATE		VIEW:	PART NO.:	
△X					4 < L ≤ 16	±0.3	CHKD		DATE		UNIT: mm	DWG NO.:	
△X					16 < L ≤ 63	±0.4	APPD		DATE		SIZE: A4	XKSIM-115	
MARK	DESCRIPTION	DATE	REVISED	APPROVED	L > 63	±0.5					WEIGHT	SHEET	REVISION
REVISIONS					UNSPECIFIED TOLERANCES		XKB INDUSTRIAL PRECISION CO., LIMITED				1.0g	1/1	A0
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